

ABSTRACT

The present invention provides a system (101) for inspecting bottom side edge (103AA) of semiconductor device, configured to capture at least one image (401) comprising of a plurality of sub-images; wherein said sub-images are of the bottom
5 side edge (103AA) of a plurality of semiconductor devices, whereby said system (101) comprises of a plurality of light sources configured to emit infra-red lights towards a bottom side edge (103AA) of a plurality of semiconductor devices rotated on at least one turntable. The present invention also provides a method of performing said inspection using said system (101).

10 (Fig. 2)